LAN Transformer – *SLT171445G241P7B8*

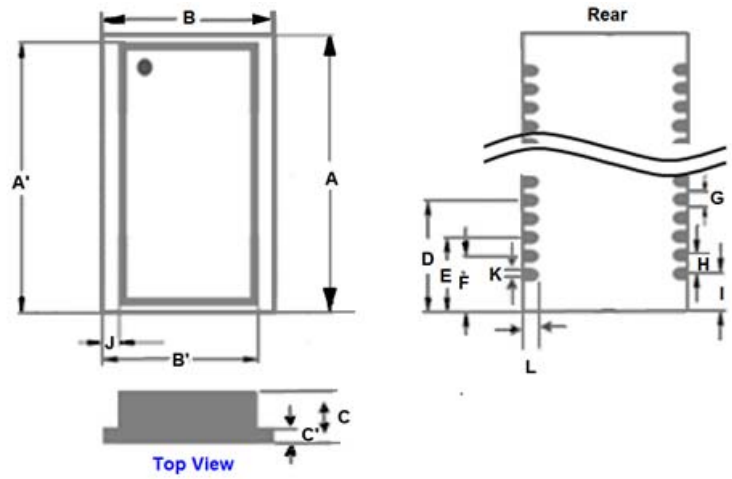
1. Part No. Expression:

S L T 1 7 1 4 4 5 G 2 4 1 P 7 B 8

(a) (b) (c) (d) (e)(f) (g)

a) Series Code
b) Dimension Code
c) Application Code
d) Pin Code
e) Center Tab
f) Pitch
g) Special Code

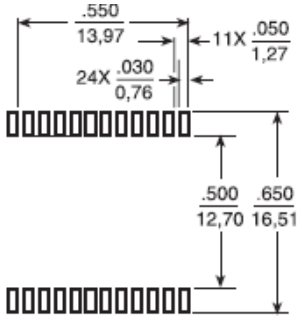
2. Configuration & Dimensions:

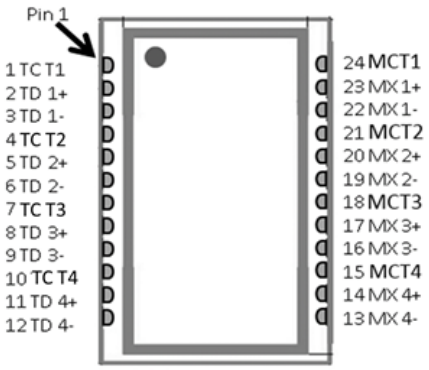


Unit: mm

A	A'	B	B'	C	C'	D	E	F
17.53±0.25	17.03±0.25	14.6±0.25	13.92±0.25	4.5 Max.	1.0±0.25	6.86±0.25	4.32±0.25	3.05±0.25
G	H	I	J	K	L			
0.80±0.05	1.27±0.25	1.78±0.25	0.67±0.05	0.30±0.05	1.10±0.25			

3. PCB Pad & Pin layout:





Measurement format: mm/inch

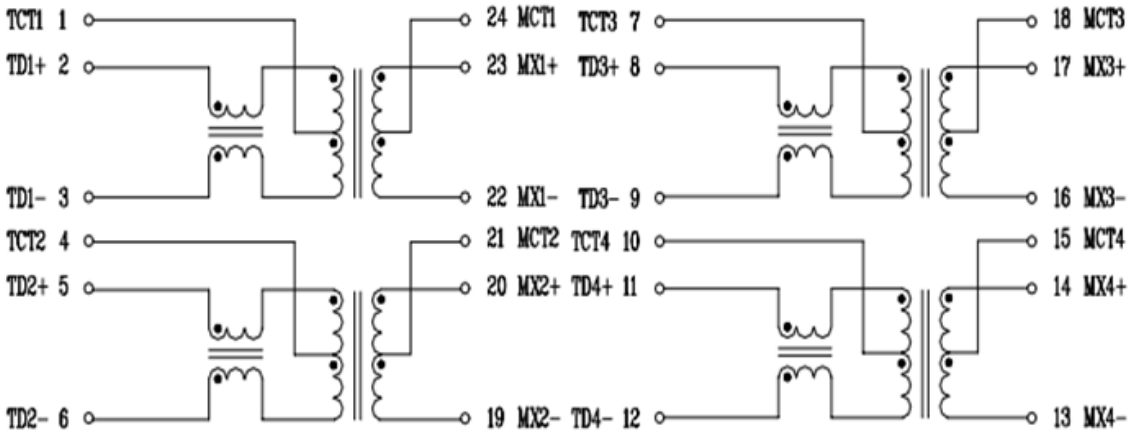
Tolerance: mm (inch) Tolerance: XX.X0 +/-0.25 (0.010)

0.XX +/-0.05 (0.002)

*All tolerance with reference to mm measurements

NOTE: Specifications subject to change without notice. Please check our website for latest information.

4. Schematic:



5. General Specification:

(a) Operating Temp.: -40°C to +85°C (including self-temperature rise)

(b) Storage Temp.: -40°C to +85°C (product without taping)

(c) Humidity Range: 85 ± 2% RH

(d) Hi- Pot Resistance Test: 1500 VAC for 1 minute

(e) Storage condition (component in its packaging)

i) Temperature: less than 40°C

ii) Humidity: 60% RH

6. Electrical Characteristics:

Part Number	Insertion Loss (dB Max.)	Return Loss (dB Min.)					Cross Talk (dB Min.)	DCMR (dB Min.)	
SLT171445G241P7B8	1~100MHz	1~30MHz	40MHz	50MHz	60~80MHz	100MHz	1~100MHz	1~60MHz	60~100MHz
	-1.1	-18	-14.4	-13.1	-12	-10	-35	-35	-30

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7. Soldering:

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

7-1 Solder Re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

7-2 Soldering Iron (Figure 2):

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note :

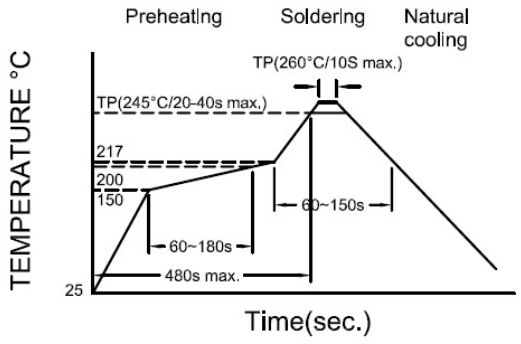
a) Preheat circuit and products to 150°C.

b) 355°C tip temperature (Max.)

c) 1.0mm tip diameter (Max.)

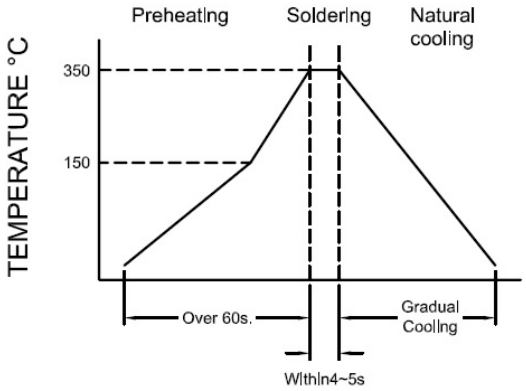
d) Use a 20 watt soldering iron with tip diameter of 1.0mm

e) Limit soldering time to 4~5 secs.



Reflow times: 3 times max

Fig.1

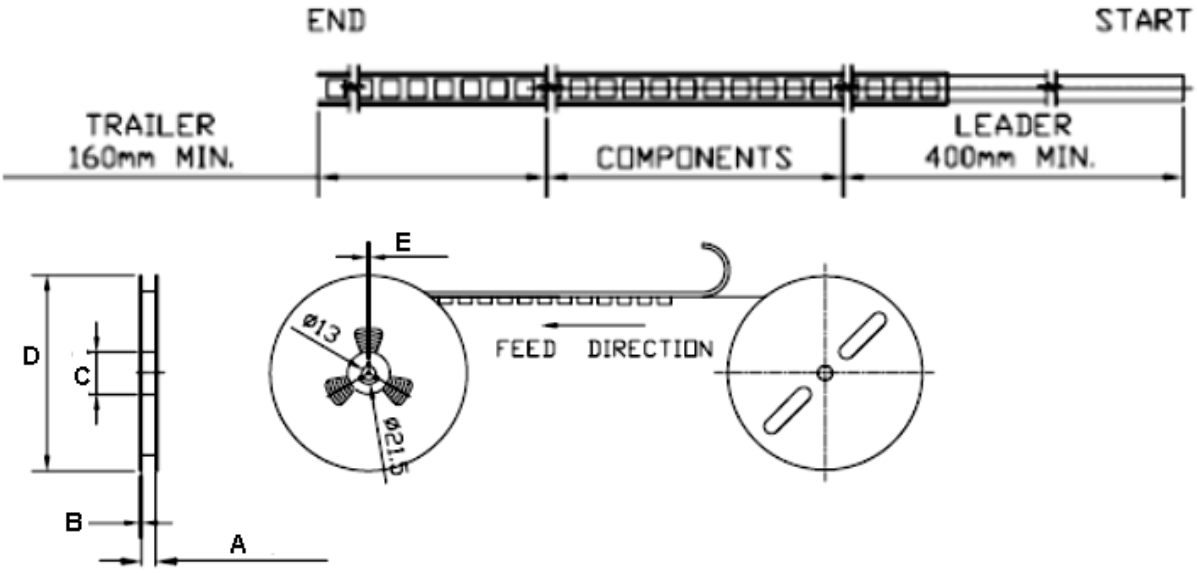


Iron Soldering times：1 times max

Fig.2

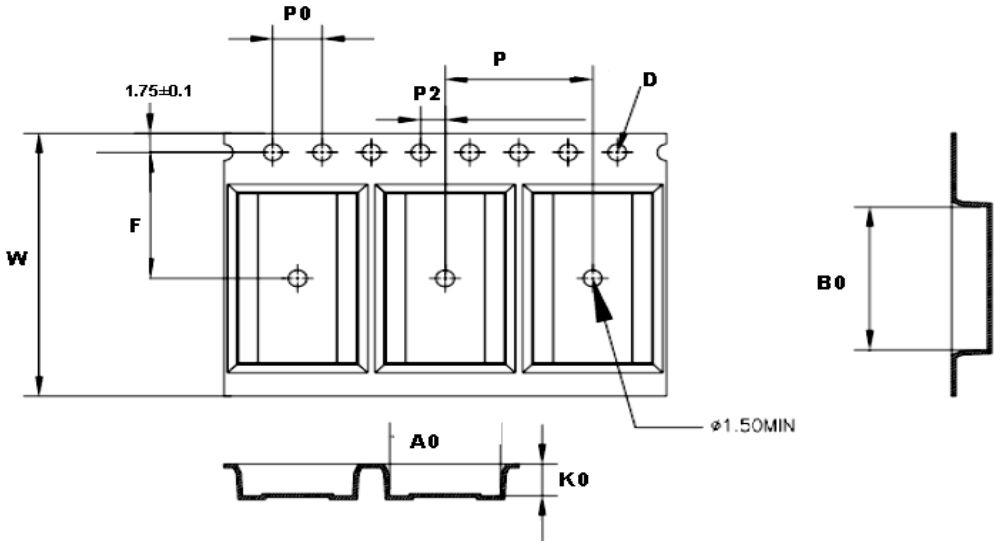
8. Packaging Information:

8-1 Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
SLT171445G241P7B8	24.4±2.0	2.1±0.15	Ø100	Ø330±2	2.5

8-2 Tape Dimension



Series	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	Po(mm)	P2(mm)	W(mm)	F(mm)	D(mm)
SLT171445G241P7B8	17.93±0.1	15.30±0.1	4.80±0.1	24.00±0.1	4.00±0.1	2.00±0.1	24.00±0.3	11.50±0.1	1.50±0.1

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8-3 Packaging Quantity

SLT	171445G241P7B8
Chip / Reel	400

Application Notice:

1. Storage Conditions:

To maintain the solderabililty of terminal electrodes:

a) Recommended products should be used within 12 months from the time of delivery.

b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.

b) Vacuum pick up is strongly recommended for individual components.

c) Bulk handling should ensure that abrasion and mechanical shock are minimized.